


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TITLE: QFN, CHIP ON LEAD (COL), 4 X 4 X 1, 0.5 PITCH, 24 TERMINAL	DOCUMENT NO: 98ASA00356D	REV: 0	
	CASE NUMBER: 2209-01	15 DEC 2011	
	STANDARD: NON-JEDEC		

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. THIS IS A NON-JEDEC REGISTERED PACKAGE.
4.  COPLANARITY APPLIES TO LEADS AND DIE ATTACH FLAG.
5. MIN. METAL GAP SHOULD BE 0.2 MM.

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